

Processing/Physical Characteristics	dry / cond	Unit	Test Standard
<b>ISO Data</b>			
<sup>[C]</sup> Molding shrinkage, parallel	0.2 / *	%	ISO 294-4, 2577
<sup>[C]</sup> Molding shrinkage, normal	0.8 / *	%	ISO 294-4, 2577

[C]: CAMPUS

Mechanical properties	dry / cond	Unit	Test Standard
<b>ISO Data</b>			
<sup>[C]</sup> Tensile Modulus	9600 / 6200	MPa	ISO 527
<sup>[C]</sup> Stress at break	180 / -	MPa	ISO 527
<sup>[C]</sup> Strain at break	3.3 / -	%	ISO 527
Flexural modulus, 23°C	9300 / 5200	MPa	ISO 178
Flexural strength	255 / -	MPa	ISO 178
<sup>[C]</sup> Charpy impact strength, +23°C	81 / 90	kJ/m <sup>2</sup>	ISO 179/1eU
<sup>[C]</sup> Charpy impact strength, -30°C	50 / -	kJ/m <sup>2</sup>	ISO 179/1eU
<sup>[C]</sup> Charpy notched impact strength, +23°C	10 / 14	kJ/m <sup>2</sup>	ISO 179/1eA

[C]: CAMPUS

Thermal properties	dry / cond	Unit	Test Standard
<b>ISO Data</b>			
<sup>[C]</sup> Melting temperature, 10°C/min	222 / *	°C	ISO 11357-1/-3
<sup>[C]</sup> Temp. of deflection under load, 1.80 MPa	204 / *	°C	ISO 75-1/-2
<sup>[C]</sup> Burning Behav. at 1.5 mm nom. thickn.	HB / *	class	IEC 60695-11-10
Yellow Card available	yes / *	-	-

[C]: CAMPUS

Electrical properties	dry / cond	Unit	Test Standard
<b>ISO Data</b>			
<sup>[C]</sup> Volume resistivity	1E13 / -	Ohm*m	IEC 62631-3-1
<sup>[C]</sup> Surface resistivity	* / 1E12	Ohm	IEC 62631-3-2
<sup>[C]</sup> Comparative tracking index	550 / -	-	IEC 60112

[C]: CAMPUS

Other properties	dry / cond	Unit	Test Standard
<sup>[C]</sup> Density	1340 / -	kg/m <sup>3</sup>	ISO 1183

[C]: CAMPUS

## Characteristics

### Processing

Injection Molding

### Applications

General Purpose

### Delivery form

Natural Color